

#### **CDRH124NP-330MT**

#### Wire Wound SMD Power Inductor

#### **FEATURES**

- High saturation current, low DCR
- Suitable for surface mounting equipment
- Close magnetic circuit design reduce leakage
- Operate temperature range ....  $-40^{\circ}$ C  $\sim +125^{\circ}$ C (Including self temp. rise)
- RoHS compliant

#### **APPLICATIONS**

 Power supply choke for small electrical equipments such as DVC, LCD display, notebook, communication equipment, OA equipment and so on.

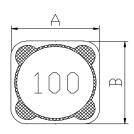
#### **Explanation of Part Number**

CDRH124 NP -330 M T

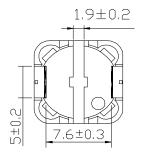
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- ♦ 1:Product Series:Wire Wound SMD Power Inductor
- ♦ 2:Dimensions:
- 3: Material Code:
- ♦ 4: Initial inductance value: 330 = 33uH
- ◆ 5:Tolerance of Inductance:M:±20%
- ♦ 6:Packing:Tape Carrier Package

### Dimensions: [mm]

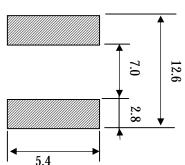






A: 12.0± 0.5 mm B: 12.0± 0.5 mm C: 5.00 Max.mm

## LAND PATTERN DIMENSIONS: [mm]





## **Electrical Properties:**

MetalLions PT/NO.	Inductance L(μH)	Test Frequency	Resistance RDC(mΩ) Max.	Isat (A)Max	Marking
CDRH124NP-330MT	33.0±20%	100kHz/0.25V	117	3.0	330

**%**Isat : Based on inductance change (△L/Lo: drop 35% Max.)



# **Reliability and Test Condition**

## **MECHANICAL**

TEST ITEM	SPECIFICATION	TEST DETAILS	
Substrate bending	∆L/Lo≦±5%	The sample shall be soldered onto the printed circuit board	
		in figure 1 and a load applied unitil the figure in the arrow	
	There shall be	direction is made approximately 3mm.(keep time 30 seconds)	
	no mechanical	PCB dimension shall the page 7/9	
	damage or elec-	F(Pressurization)	
	trical damege.	Л	
		R5 45±2 45±2 10 20 R340	
		PRESSURE ROD figure-1	
Vibration	∆L/Lo≦±5%	The sample shall be soldered onto the printed circuit board	
		and when a vibration having an amplitude of 1.52mm	
	There shall be	and a frequency of from 10 to 55Hz/1 minute repeated should	
	no mechanical	be applied to the 3 directions (X,Y,Z) for 2 hours each.	
	damage.	(A total of 6 hours)	
Solderability	New solder	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated	
Colderability	More than 90%	over the whole of the sample before hard, the sample shall	
		then be preheated for about 2 minutes in a temperature of	
		130∼150℃ and after it has been immersed to a depth 0.5mm	
		below for 3±0.2 seconds fully in molten solder M705 with	
		a temperature of 245±5℃.	
		More than 90% of the electrode sections shall be couered	
		with new solder smoothly when the sample is taken out of	
		the solder bath.	



## **MECHANICAL**

TEST ITEM	SPECIFICATION	
Resistance to	There shall be	Temperature profile of reflow soldering
Soldering heat	no damage or	
(reflow soldering)	problems.	Soldering (Peak temperature 260±3°C 10 sec 250 250 250 250 250 250 250 250 250 250

### **ELECTRICAL**

TEST ITEM	SPECIFICATION	TEST DETAILS
Insulation	There shall be	DC 100V voltage shall be applied across this sample of top
resistance	no other	surface and the terminal.
	damage or	The insulation resistance shall be more than $1 \times 10^8 \Omega$ .
	problems.	
Dielectric	There shall be	AC 100V voltage shall be applied for 1 minute acrosset the top
withstand	no other	surface and the terminal of this sample
voltage	damage or	
	problems.	
Temperature	∆L/L20°C ≦±10%	The test shall be performed after the sample has stabilized in
characteristics	0~2000 ppm/℃	an ambient temperature of -20 to +85℃,and the value
		calculated based on the value applicable in a normal
		temperature and narmal humidity shall be △L/L20°C ≦±10%.



# **ENVIROMENT CHARACTERISTICS**

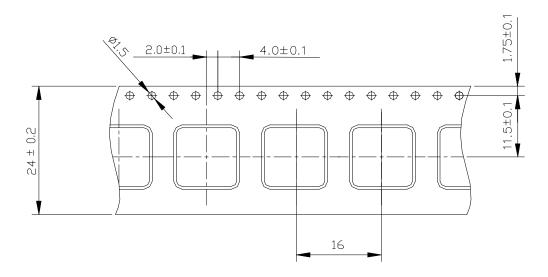
TEST ITEM			SPECIFICATION			
High temperature	∆L/Lo≦±5%	The sample shall be left for 96±4 hours in an atmospere with				
storage		a temperature of 85±2 $^{\circ}$ C and a normal humidity.				
	There shall be	Upon compl	Upon completion of the measurement shall be made after the			
	no mechanical	sample has been left in a normal temperature and normal				
	damage.	humidity for	1 hour.			
Low temperature	∆L/Lo≦±5%	The sample shall be left for 96±4 hours in an atmosphere with				
storage		a temperatu	a temperature of -25±3℃.			
	There shall be	Upon completion of the test, the measurement shall be made				
	no mechanical	after the sample has been left in a normal temperature and				
	damage.	normal hum	normal humidity for 1 hour.			
Change of	∆L/Lo≦±5%	The sample shall be subject to 5 continuos cycles, such as shown				
temperature		in the table 2 below and then it shall be subjected to standard				
	There shall be	atmospheric conditions for 1 hour, after which measurement				
	no other dama-	shall be made.				
	ge of problems					
			table 2			
			Temperature	Duration		
		1	<b>−25±3</b> °C	30 min.		
			(Themostat No.1)			
		2	Standard	No.1→No.2		
			atmospheric	110.11 - 110.2		
		3	<b>85±2℃</b>	30 min.		
			(Themostat No.2)			
		4	Standard	No.2→No.1		
			atmospheric	11012		
Moisture storage	∆L/Lo≦±5%	The sample	The sample shall be left for 96±4 hours in a temperature of			
		40±2℃ and	40±2℃ and a humidity(RH) of 90∼95%.			
	There shall be	Upon completion of the test, the measurement shall be made				
	no mechanical	after the sample has been left in a normal temperature and				
	damage.	las a successi de consti	normal humidity more than 1 hour.			

The sample shall be reflow soldered onto the printed circuit board in every test.



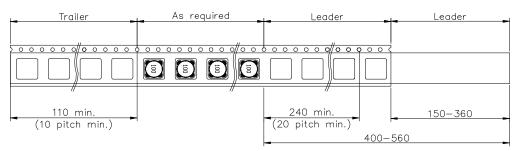
#### **PACKAGING**

### **CARRIER TAPE DIMENSIONS (mm)**



## **TAPING DIMENSIONS (mm)**





## **REEL DIMENSIONS (mm)**

